

SMD - CHIP LED

HIGH POWER OUTPUT

NEW



SR 10 HR

hyper red

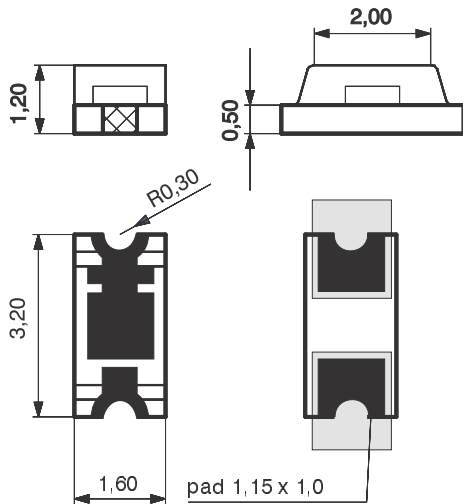
MADE IN GERMANY

2/99

ALL MEASUREMENTS IN mm

Tol.: ±0,10

Features



Chip on PCB, Surface Mounting Device
Center Chip Position, also Available ±0,05 mm
End-to-End and Side-to-Side Stackable
Down to a Pitch of 1,6mm

Description

The Solderpads 1,15x1,0mm² Provide an Excellent Heat Sink
Ideal for Sensor Applications.
Small true Chip-LED to Build Custom Configurations.
Available on Special order in 8mm Blister Tape or Solid
Strips of up to 12 pcs with a true Pitch of 1,6 mm.

PRELIMINARY

MAXIMUM RATINGS

Power Dissipation	P_{tot}	130 mW
Peak Forward Current	$I_{FSM}(10\mu s)$	800 mA
Continuous Forward Current	I_F	75 mA
Junction Temperature	T_j	120°C
Storage Temperature	T_{st}	-25 to 120°C
Operating Temperature	T_{op}	-25 to 80°C
Soldering Temperature	$T_{sold}(10sec)$	250°C

OPTICAL AND ELECTRICAL CHARACTERISTICS

$I_F = 20\text{ mA}$, Ambient Temperature = 25°C

	min.	typ.	max.	
Luminous Intensity	8,0	15,0		mcd
(at 2 mA)	1,3	2,8		
Peak Emission Wavelength	650	655	660	nm
Spectral Half Bandwidth		20		nm
Forward Voltage		1,8	2,1	V
Reverse Leakage		100		μA
Reverse Voltage	5	10		V

SPECIALITY: very accurate die attach

SMD - CHIP LED

HIGH POWER OUTPUT

NEW



SR 10 HR-B

hyper red

MADE IN GERMANY

2/99

ALL MEASUREMENTS IN mm

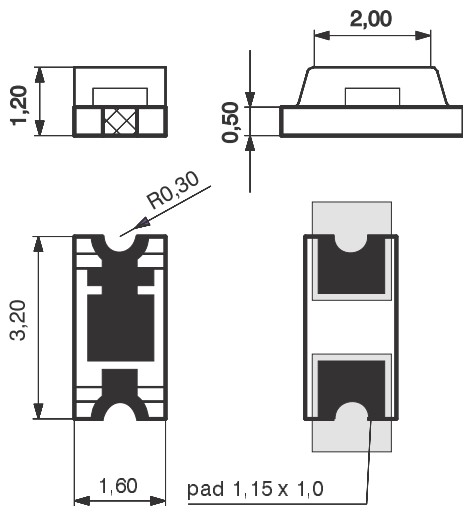
Tol.: ±0,05

Features

Chip on PCB, Surface Mounting Device
Center Chip Position, also Available ±0,1 mm
End-to-End and Side-to-Side Stackable
Down to a Pitch of 1,6mm

Description

The Solderpads 1,15x1,0mm² Provide an Excellent Heat Sink
Ideal for Sensor Applications.
Small true Chip-LED to Build Custom Configurations.
Available on Special order in 8mm Blister Tape or Solid
Strips of up to 12 pcs with a true Pitch of 1,6 mm.



PRELIMINARY

MAXIMUM RATINGS

Power Dissipation	P_{tot}	130 mW
Peak Forward Current	$I_{FSM}(10\mu s)$	800 mA
Continuous Forward Current	I_F	75 mA
Junction Temperature	T_j	120°C
Storage Temperature	T_{st}	-25 to 120°C
Operating Temperature	T_{op}	-25 to 80°C
Soldering Temperature	$T_{sold}(10sec)$	250°C

OPTICAL AND ELECTRICAL CHARACTERISTICS

$I_F = 20\text{ mA}$, Ambient Temperature = 25°C

	min.	typ.	max.	
Luminous Intensity	8,0	15,0		mcd
(at 2 mA)	1,3	2,8		
Peak Emission Wavelength	650	655	660	nm
Spectral Half Bandwidth		20		nm
Forward Voltage		1,8	2,1	V
Reverse Leakage		100		μA
Reverse Voltage	5	10		V

SPECIALITY: very accurate die attach

SMD - CHIP LED

HIGH POWER OUTPUT

NEW



SR10UR

ultra red

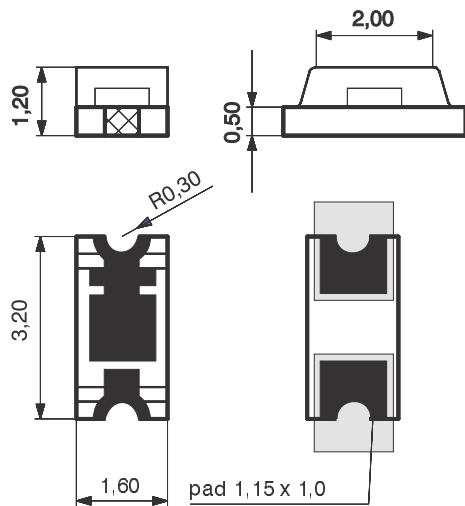
MADE IN GERMANY

2/99

ALL MEASUREMENTS IN MM

Tol.: ±0,10

Features



Chip on PCB, Surface Mounting Device
Center Chip Position, also Available ±0,05 mm
End-to-End and Side-to-Side Stackable
Down to a pitch of 1,6mm

Description

The Solderpads 1,15x1,0mm² Provide an Excellent heat sink
Ideal for Sensor Applications.
Small true Chip-LED to Build Custom Configurations.
Available on Special order in 8mm Blister tape or Solid
Strips of up to 12 pcs with a true Pitch of 1,6 mm.

PRELIMINARY

MAXIMUM RATINGS

Power Dissipation	P_{tot}	130 mW
Peak Forward Current	$I_{FSM}(10\mu s)$	600 mA
Continuous Forward Current	I_F	75 mA
Junction Temperature	T_j	120°C
Storage Temperature	T_{st}	-25 to 120°C
Operating Temperature	T_{op}	-25 to 80°C
Soldering Temperature	$T_{sold}(10sec)$	250°C

OPTICAL AND ELECTRICAL CHARACTERISTICS

Ambient Temperature = 25°C

	min.	typ.	max.	
Luminous Intensity	18,0	28,0		mcd
Peak Emission Wavelength		660		nm
Spectral Half Bandwidth		20		nm
Forward Voltage		1,8	2,2	V
Reverse Leakage			100	µA
Reverse Voltage	5	20		V

SPECIALITY: very accurate die attach

SMD - CHIP LED

HIGH POWER OUTPUT

NEW



SR10UR-B

ultra red

MADE IN GERMANY

2/99

ALL MEASUREMENTS IN MM

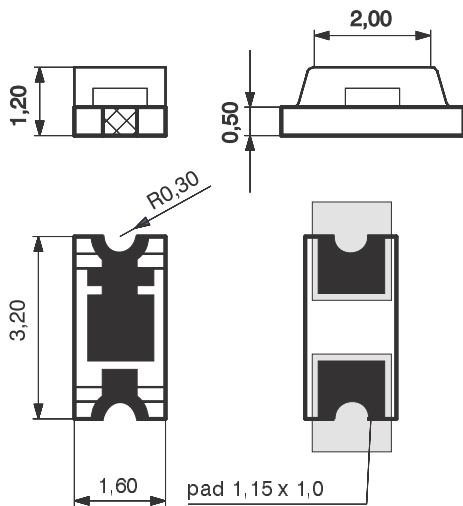
Tol.: ±0,05

Features

Chip on PCB, Surface Mounting Device
Center Chip Position, also Available ±0,1 mm
End-to-End and Side-to-Side Stackable
Down to a pitch of 1,6mm

Description

The Solderpads 1,15x1,0mm² Provide an Excellent heat sink
Ideal for Sensor Applications.
Small true Chip-LED to Build Custom Configurations.
Available on Special order in 8mm Blister tape or Solid
Strips of up to 12 pcs with a true Pitch of 1,6 mm.



PRELIMINARY

MAXIMUM RATINGS

Power Dissipation	P_{tot}	130 mW
Peak Forward Current	$I_{FSM}(10\mu s)$	600 mA
Continuous Forward Current	I_F	75 mA
Junction Temperature	T_j	120°C
Storage Temperature	T_{st}	-25 to 120°C
Operating Temperature	T_{op}	-25 to 80°C
Soldering Temperature	$T_{sold}(10sec)$	250°C

OPTICAL AND ELECTRICAL CHARACTERISTICS

Ambient Temperature = 25°C

	min.	typ.	max.	
Luminous Intensity	18,0	28,0		mcd
Peak Emission Wavelength		660		nm
Spectral Half Bandwidth		20		nm
Forward Voltage		1,8	2,2	V
Reverse Leakage			100	µA
Reverse Voltage	5	20		V

SPECIALITY: very accurate die attach